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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

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August 2016

FDMC86265P

P-Channel PowerTrench® MOSFET -150 V, -2.6 A, 1.2 Ω

Features

- Max $r_{DS(on)} = 1.2 \Omega$ at $V_{GS} = -10 \text{ V}$, $I_D = -1 \text{ A}$
- Max $r_{DS(on)} = 1.4 \Omega$ at $V_{GS} = -6 \text{ V}$, $I_D = -0.9 \text{ A}$
- Very Low RDS-on Mid Voltage P-channel Silicon Technology Optimised for Low Qg
- This product is optimised for fast switching applications as well as load switch applications.
- 100% UIL Tested
- RoHS Compliant

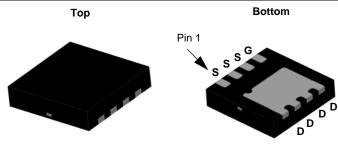


General Description

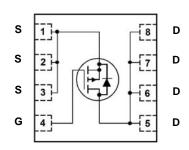
This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been optimized for the on-state resistance and yet maintain superior switching performance.

Applications

- Active Clamp Switch
- Load Switch







MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted.

Symbol	Parameter			Ratings	Units	
V _{DS}	Drain to Source Voltage			-150	V	
V_{GS}	Gate to Source Voltage			±25	V	
	Drain Current -Continuous	T _C = 25 °C	(Note 5)	-2.6		
	-Continuous	T _C = 100 °C	(Note 5)	-1.65		
'D	-Continuous	T _A = 25 °C	(Note 1a)	-1	A	
	-Pulsed		(Note 4)	-9		
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	6	mJ	
В	Power Dissipation	T _C = 25 °C		16	W	
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.3	VV	
T _J , T _{STG}	Operating and Storage Junction Tempera	ature Range		-55 to + 150	°C	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	7.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a	53	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC86265P	FDMC86265P	Power 33	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-150			V
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25 °C		-125		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -120 V, V _{GS} = 0 V			-1	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-2	-3.2	-4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25 °C		5		mV/°C
		$V_{GS} = -10 \text{ V}, I_D = -1 \text{ A}$		0.86	1.2	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = -6 \text{ V}, I_{D} = -0.9 \text{ A}$		0.95	1.4	Ω
, ,		$V_{GS} = -10 \text{ V}, I_D = -1 \text{ A}, T_J = 125 \text{ °C}$		1.53	2.2	
9 _{FS}	Forward Transconductance	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ A}$		1.9		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 75.V.V 0.V		158	210	pF
Coss	Output Capacitance	$V_{DS} = -75 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$		16	25	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12		0.7	5	pF
R_{α}	Gate Resistance		0.1	3	7.5	Ω

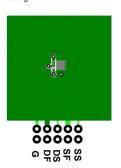
Switching Characteristics

t _{d(on)}	Turn-On Delay Time		5.8	12	ns
t _r	Rise Time	V _{DD} = -75 V, I _D = -1 A,	2.2	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$	8	16	ns
t _f	Fall Time		6.4	13	ns
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to -10 V } V_{DD} = -75 \text{ V},$	2.8	4	nC
Q _{gs}	Total Gate Charge	I _D = -1 A	0.8		nC
Q _{ad}	Gate to Drain "Miller" Charge		0.7		nC

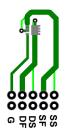
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -1 \text{ A}$	(Note 2)	-0.87	-1.3	V
t _{rr}	Reverse Recovery Time	I = 1 A di/dt = 100 A/us		50	80	ns
Q _{rr}	Reverse Recovery Charge	$I_F = -1 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		78	124	nC

^{1.} R_{0,1A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1C} is guaranteed by design while R_{0,CA} is determined by the user's board design.



a) 53 °C/W when mounted on a 1 in² pad of 2 oz copper



b) 125 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300 µs, Duty cycle < 2.0%.
 3. Starting T_J = 25 °C; P-ch: L =3 mH, I_{AS} = -2 A, V_{DD} = -150 V, V_{GS} = -10 V. 100% test at L = 0.1 mH, I_{AS} = -9 A.
 4. Pulsed Id please refer to Fig 11 and Fig 24 SOA graph for more details.
 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

Typical Characteristics T_J = 25 °C unless otherwise noted.

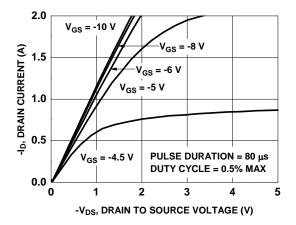


Figure 1. On Region Characteristics

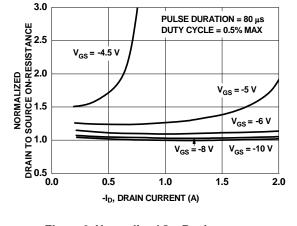


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

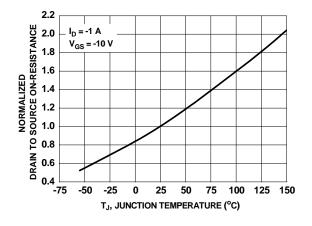


Figure 3. Normalized On Resistance vs. Junction Temperature

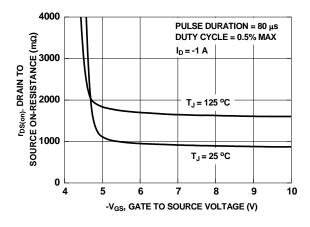


Figure 4. On-Resistance vs. Gate to Source Voltage

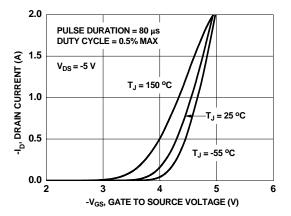


Figure 5. Transfer Characteristics

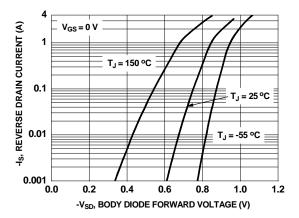


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

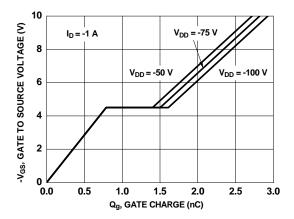


Figure 7. Gate Charge Characteristics

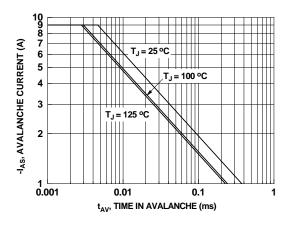


Figure 9. Unclamped Inductive Switching Capability

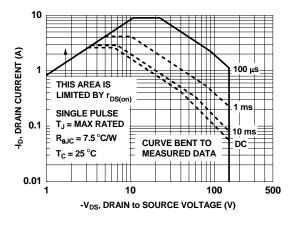


Figure 11. Forward Bias Safe Operating Area

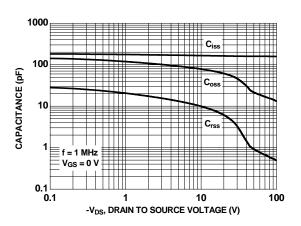


Figure 8. Capacitance vs. Drain to Source Voltage

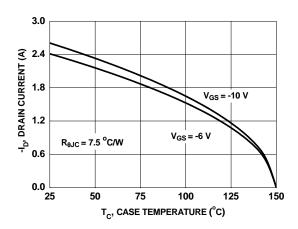


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

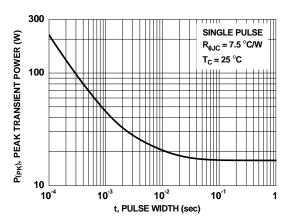


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

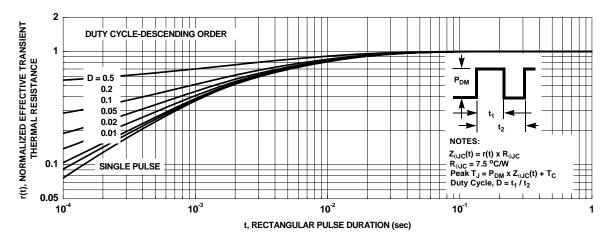
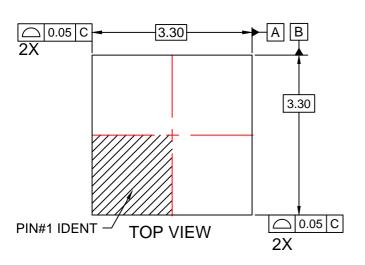
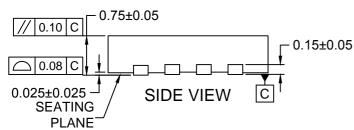
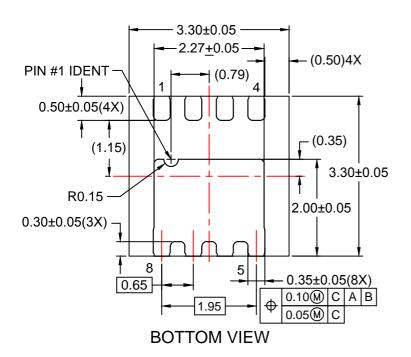
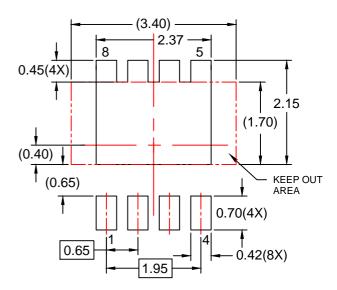


Figure 13. Junction-to-Case Transient Thermal Response Curve









RECOMMENDED LAND PATTERN

NOTES:

- A. DOES NOT CONFORM TO JEDEC REGISTRATION MO-229
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MLP08Srev3.



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